

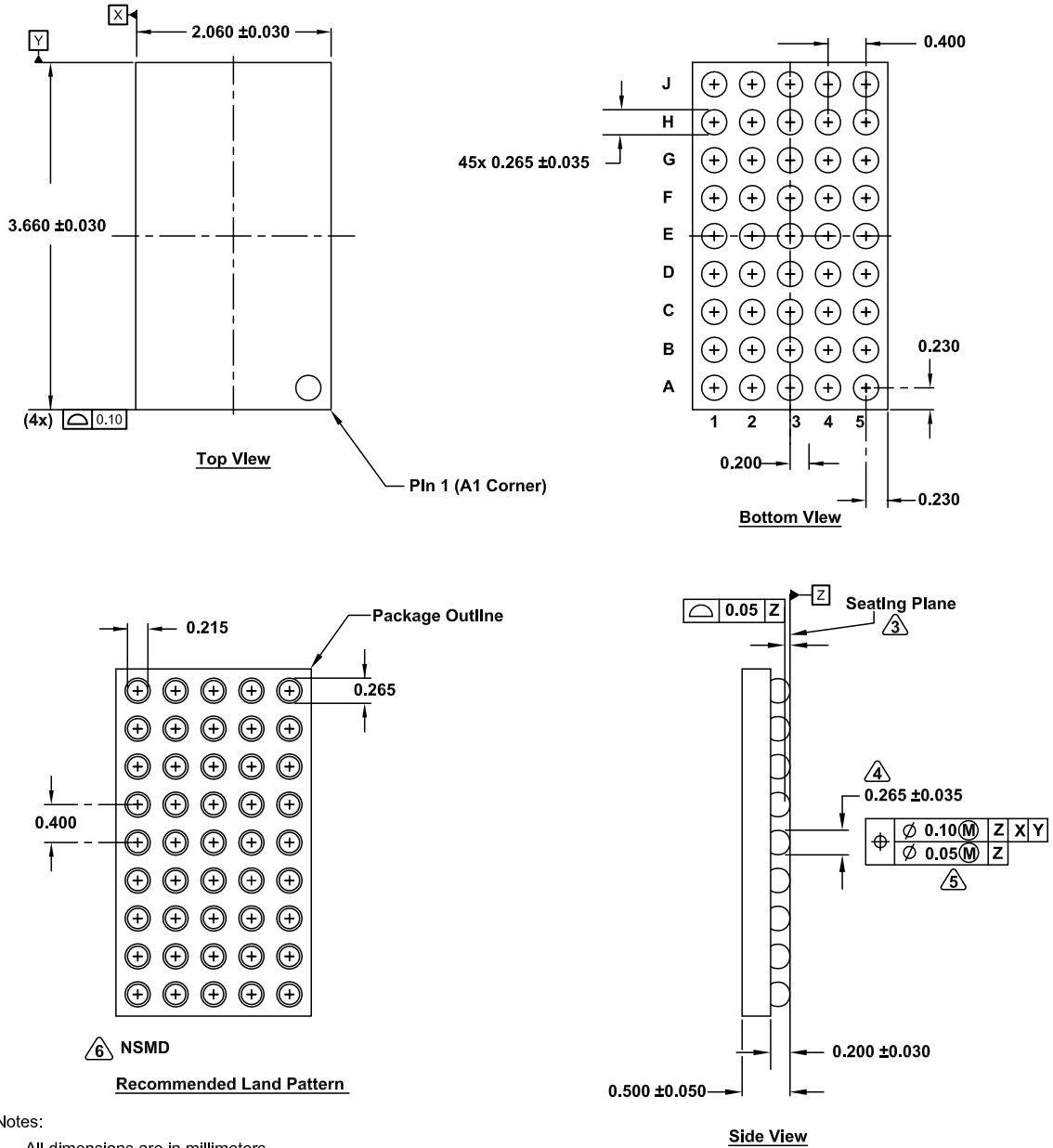
Plastic Packages for Integrated Circuits

Package Outline Drawing

W5x9.45

5x9 Array 45 Balls with 0.4mm Pitch Wafer Level Chip Scale Package (WLCSP)

Rev 0, 1/20



Notes:

- All dimensions are in millimeters.
- Dimensions and tolerances per ASMEY 14.5-1994.
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum Z .
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Renesas TB451.